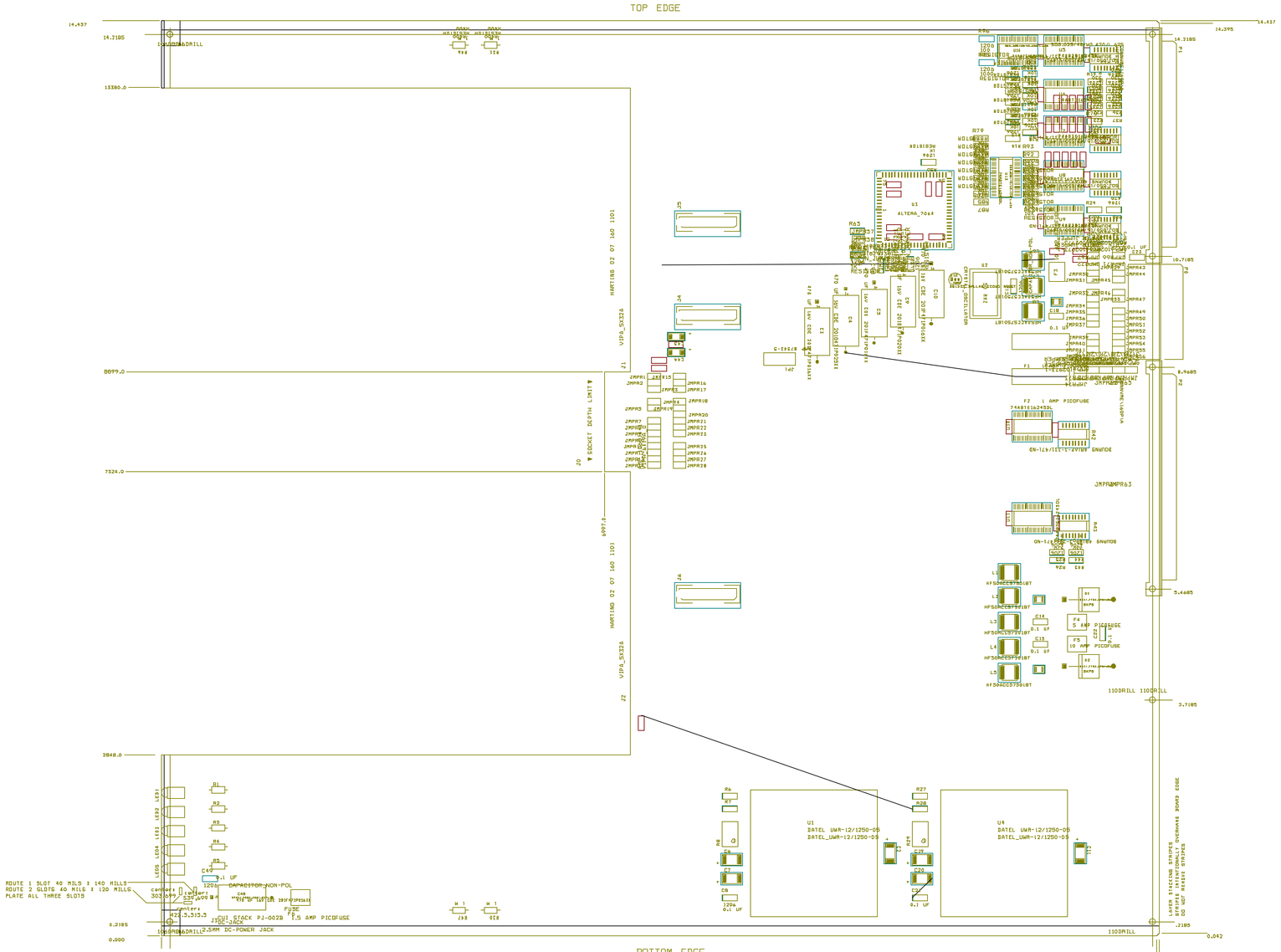

Finished board thickness is .093" +/-.008".
Mill solder side of board along both top and bottom edges.
Mill width is 0.098" +0.000" -0.008" in from edges.
Finished board thickness of milled area to be 0.063" +/-0.008".

Materials FR-4 with Tg of 140 or greater.
Maximum Panel size of ☐ 12" ■ 18" ☐ 24"
Horizontal with limits: No greater than -.001" in 1/2 oz. Cu layers.
No greater than -.002" in 1 oz. Cu layers.
No greater than -.004" in 2 oz. Cu layers.
Copper plating on PTH walls: Minimum 1 mil plating in the hole.
Drill Hole Tolerances 0.050 in. diameter or less: +/- 0.003 in.
Drill Hole Tolerance: 0.050 in. diameter or more: +/- 0.007 in.
No drill hole shall breakout from any pad. Minimum annular copper ring radius: 0.002 in.
SMOBC
LPI Soldermask
Silkscreen color: White
HASL
Testing Requirements: ☐ None ■ Flying Probe ☐ Clamshell

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Gerber Lists
- TOP (Drill Tape)
- FAB (Fabrication Drwg)
- DTS (Drill Tape Summary)
- AST (Top Assembly)
- SPT (Solder Paste Top)
- SST (Silkscreen Top)
- SMT (Solder Mask Top)
- TOP (Top Signal)
- SND (Ground Plane)
- IN1 (Inner Signal 1)
- IN2 (Inner Signal 2)
- IN3 (Inner Signal 3)
- IN4 (Inner Signal 4)
- APP (Aperture List)
- GRO (Drill Drwg)
- GTO (Drill Extended Gerber)
- ASB (Bottom Assembly)
- SPB (Solder Paste Bottom)
- SSB (Silkscreen Bottom)
- SMB (Solder Mask Bottom)
- BOT (Bottom Signal)
- PWR (Power Plane)
- IN5 (Inner Signal 5)
- IN6 (Inner Signal 6)
- IL1 (Inner Signal 11)
- IL2 (Inner Signal 12)

14 Cu LAYER STACKUP:
LAYER 1: TOP (60 OHM MICROSTRIP)
LAYER 2: GND (GROUND PLANE)
LAYER 3: IN1 (60 OHM STRIPLINE)
LAYER 4: IN2 (60 OHM STRIPLINE)
LAYER 5: GND (GROUND PLANE)
LAYER 6: IN3 (60 OHM STRIPLINE)
LAYER 7: IN4 (60 OHM STRIPLINE)
LAYER 8: GND (GROUND PLANE)
LAYER 9: IL1 (BIPOLAR 12V PLANE)
LAYER 10: IN6
LAYER 11: PWR (POWER PLANE)
* FAB NOTE: PLEASE SEE THIS AREA TO PAD THE BOARD THICKNESS, SO AS TO INCREASE THE DISTANCE BETWEEN LAYERS 12 AND 13.
WE WANT LAYER 12 TO COUPLE TO LAYER 13 (GROUND) FOR IMPEDANCE CONTROL.
LAYER 12: IN5 (60 OHM MICROSTRIP TO LAYER 13, WITH B-10 INSTEAD OF AIR AS TOP DIELECTRIC)
LAYER 13: GND (GROUND PLANE)
LAYER 14: BOT (60 OHM MICROSTRIP)